

Amendments to the Claims

The following listing of claims will replace all prior versions of claims in the application.

- 1-9. (canceled)
10. (currently amended) A heat-curable adhesive composition comprising:
an ethylene-glycidyl (meth)acrylate copolymer;
a low density polyethylene;
an ethylene- α -olefin copolymer; and
a heat curing agent for said ethylene-glycidyl (meth)acrylate copolymer, wherein
said heat curing agent comprises a rosin having a carboxyl group in the molecule.
11. (previously presented) The heat-curable adhesive composition of claim 10,
wherein the minimum density of said low density polyethylene is at least about 0.910 as
measured according to ASTM D1248-84.
12. (previously presented) The heat-curable adhesive composition of claim 10,
wherein the maximum density of said low density polyethylene is up to about 0.925 as measured
according to ASTM D1248-84.
13. (previously presented) The heat-curable adhesive composition of claim 10,
wherein, in said ethylene- α -olefin copolymer, the polymerization ratio of ethylene to α -olefin is
from about 90:10 to about 10:90.
14. (previously presented) The heat curable adhesive composition of claim 10,
wherein the minimum density of said ethylene- α -olefin copolymer is about 0.850 as measured
according to ASTM D1248-84.

15. (previously presented) The heat curable adhesive composition of claim 10, wherein the maximum density of said ethylene- α -olefin copolymer is up to about 0.909 as measured according to ASTM D1248-84.

16. cancelled.

17. cancelled.

18. (previously presented) The heat-curable adhesive composition of claim 17, wherein said film has a thickness from about 5 to about 80 μm .

19. (previously presented) The heat-curable adhesive composition of claim 10, wherein, after post-curing, the composition has a dielectric constant of about 2.5 or less, and a dielectric loss tangent of about 0.015 or less when measured at the frequency of about 1 GHz.

20. cancelled.